



Material Content Data Sheet



Sales Product Name		SPA07N65C3		Issued		29. August 2013		
MA#		MA000385219						
Package		PG-TO220-3-111		Weight*		2240.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.883	0.22	0.22	2180	2180
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		500	
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150	
	non noble metal	copper	7440-50-8	1118.332	49.93	50.00	499245	499895
wire	non noble metal	aluminium	7429-90-5	0.704	0.03	0.03	314	314
encapsulation	organic material	carbon black	1333-86-4	2.209	0.10		986	
	plastics	epoxy resin	-	207.662	9.27		92705	
	inorganic material	silicondioxide	60676-86-0	894.715	39.94	49.31	399418	493109
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3545	3545
plating	non noble metal	nickel	7440-02-0	0.305	0.01		136	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	136
solder	non noble metal	antimony	7440-36-0	0.184	0.01		82	
	noble metal	silver	7440-22-4	0.460	0.02		205	
	non noble metal	tin	7440-31-5	1.196	0.05	0.08	534	821
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com